2SC4808

Silicon NPN epitaxial planar type

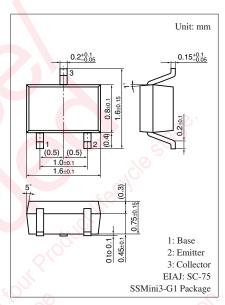
For UHF band low-noise amplification

Features

- Low noise figure NF
- High forward transfer gain $|S_{21e}|^2$
- High transition frequency f_T
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	15	V
Collector-emitter voltage (Base open)	V _{CEO}	10	v
Emitter-base voltage (Collector open)	V _{EBO}	2	V
Collector current	I _C	80	mA
Collector power dissipation	P _C	125	mW
Junction temperature	Tj	125	°C
Storage temperature	T _{stg}	-55 to +125	°C



Marking Symbol: 3M

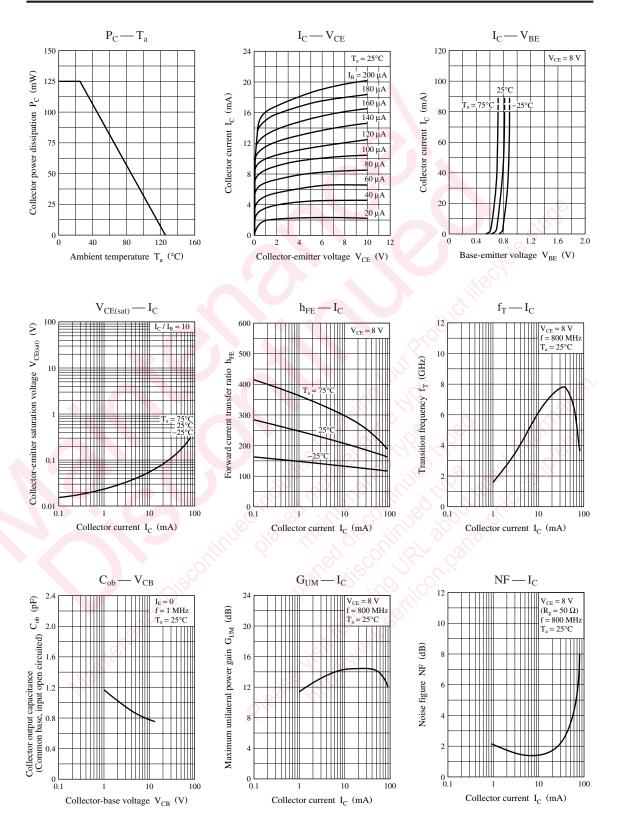
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu A, I_{\rm E} = 0$	15	3		V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 100 \ \mu \text{A}, I_{\rm B} = 0$	10			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 10 \text{ V}, I_E = 0$	$\sqrt{2}$		1	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 2 V, I_C = 0$			1	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CE} = 8 V, I_C = 20 mA$	50	150	300	
Transition frequency	f _T	$V_{CE} = 8 \text{ V}, I_{C} = 15 \text{ mA}, f = 0.8 \text{ GHz}$	5	6		GHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		0.7	1.2	pF
Forward transfer gain	S _{21e} ²	$V_{CE} = 8 \text{ V}, I_{C} = 15 \text{ mA}, f = 0.8 \text{ GHz}$	11	14		dB
Maximum unilateral power gain	G _{UM}	$V_{CE} = 8 \text{ V}, I_{C} = 15 \text{ mA}, f = 0.8 \text{ GHz}$		15		dB
Noise figure	NF <	$V_{CE} = 8 \text{ V}, \text{ I}_{C} = 7 \text{ mA}, \text{ f} = 0.8 \text{ GHz}$		1.3	2.0	dB

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Pulse measurement

Panasonic



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